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| · · | Application No. | Applicant(s) |
|--|--|-----------------------------|
| Notice of Allowability | 10/696,918 | ROBERT S. VINSON |
| | Examiner | Art Unit |
| | Thanh Y. Tran | 2822 |
| The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308. | | |
| 1. X This communication is responsive to 7/24/06. | | |
| 2. The allowed claim(s) is/are 10,15,16 and 18. | | |
| 3. Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some* c) None of the: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this national stage application from the International Bureau (PCT Rule 17.2(a)). * Certified copies not received: | | |
| Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application. THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. | | |
| 4. A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient. | | |
| 5. CORRECTED DRAWINGS (as "replacement sheets") must be submitted. | | |
| (a) ☐ including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached | | |
| 1) hereto or 2) to Paper No./Mail Date | | |
| (b) ☐ including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date | | |
| Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d). | | |
| 6. DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL. | | |
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| Attachment(s) | | |
| 1. Notice of References Cited (PTO-892) | 5. Notice of Informal P | ' ' |
| 2. Notice of Draftperson's Patent Drawing Review (PTO-948) | 6. ☐ Interview Summary Paper No./Mail Dat | |
| 3. Information Disclosure Statements (PTO/SB/08), Paper No./Mail Date | 7. 🗌 Examiner's Amendo | |
| 4. Examiner's Comment Regarding Requirement for Deposit of Biological Material | 8. 🛭 Examiner's Stateme | nt of Reasons for Allowance |
| | . 9. Other | |
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DETAILED ACTION

Allowable Subject Matter

- 1. Claims 10, 15-16, and 18 are allowed.
- 2. The following is an examiner's statement of reasons for allowance:

The prior art of record and to the examiner's knowledge does not teach or render obvious, at least to the skilled artisan, the instant invention regarding:

An integrated circuit chip module comprising: a substrate; at least one integrated circuit die is mounted directly on the substrate; a plurality of decoupling capacitor assemblies are mounted in series directly on the integrated circuit die, each decoupling capacitor assembly comprising: a capacitor carrier is secured onto the exposed surface of the integrated circuit die, a thin film metallization layer is formed directly on the capacitor carrier; a conductive adhesive layer is applied directly onto the thin film metallization layer, a decoupling capacitor is secured directly onto the thin film metallization layer by the conductive adhesive layer; and a wire bond is extending from the thin film metallization layer to a logic pin of the integrated circuit die, as recited in claim 10. Claims 15-16 and 18 are dependent upon independent claim 10.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

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Contact Information

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thanh Y. Tran whose telephone number is (571) 272-2110. The examiner can normally be reached on M-F (9-6:30pm).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra Smith can be reached on (571) 272-2429. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

TYT

Zandra V. Smith

Supervisory Patent Examiner

27 Sept. 2004